



SOT638-1

plastic thermal enhanced thin quad flat package; 100 leads;
body 14 x 14 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP100
Package type industry code	HTQFP100
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	2-2-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	100	-	



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2. Package outline

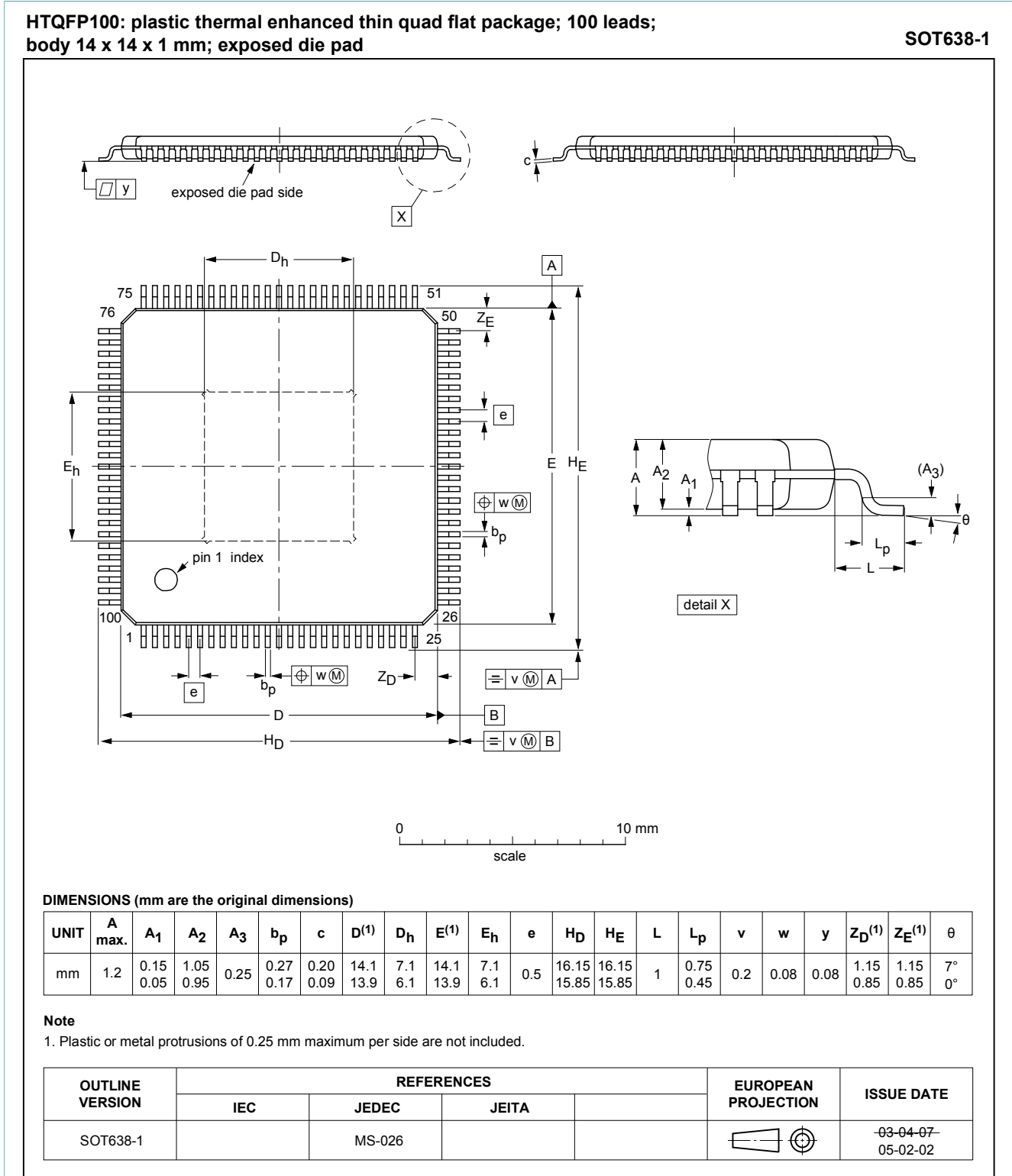


Fig. 1. Package outline HTQFP100 (SOT638-1)

3. Soldering

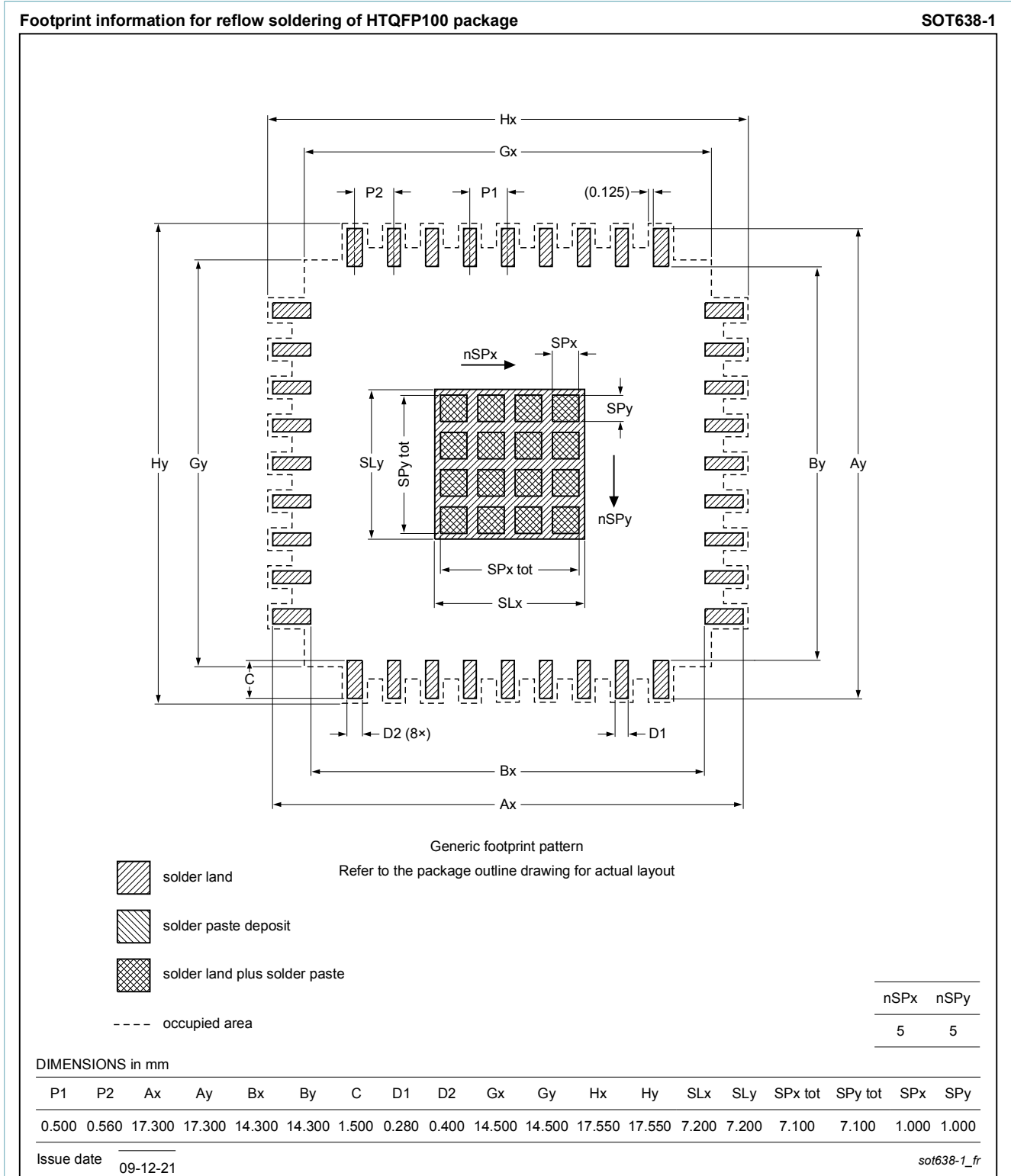


Fig. 2. Reflow soldering footprint for HTQFP100 (SOT638-1)

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4. Legal information

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